

# PRODUCT SPECIFICATION

*Part Number*  
**PDC302-CxPxxx**

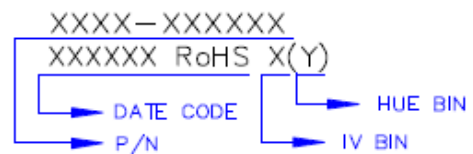
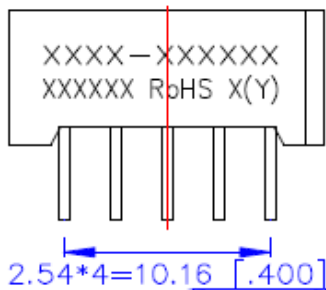
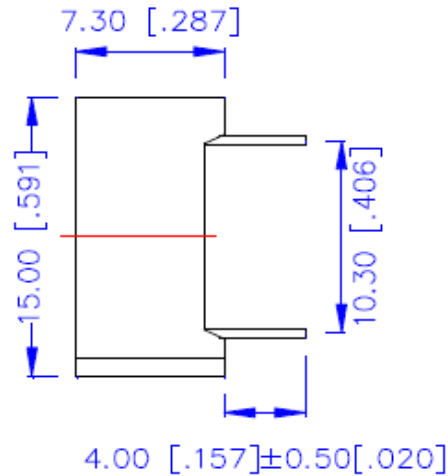
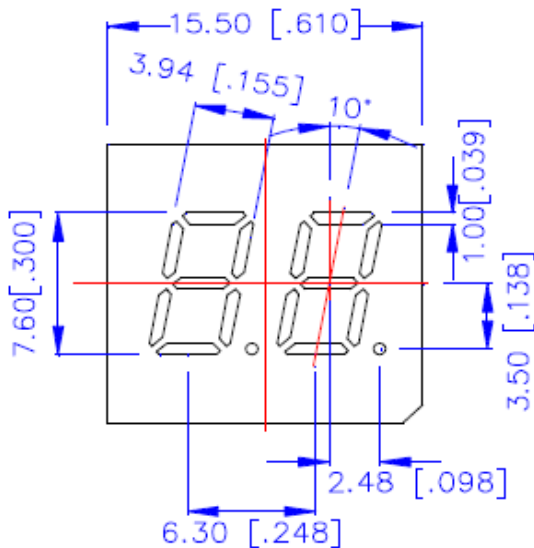
## Details

- 0.3”(7.60mm) Display
- 2 Digit, 7 Segment
- Common Anode or Cathode
- AlInGaP or InGaN dice used

## Features

- Low power consumption
- RoHS Compliant
- Gray Face, White Segments or Black Face, White Segments
- Easy mounting on PCB or socket

## Mechanical Dimensions



### Notes:

1. Dimensions in millimeters [inch], and tolerance is  $\pm 0.25$  [.010] and angle is  $\pm 1^\circ$  unless otherwise noted.
2. Bending  $\leq$  Length\*1%
3. All pins are  $\varnothing 0.51$  [.020]  $\pm 0.1$  [.004]
4. Specifications subject to change without notice



**Device Selection Guide**

Model Number	Chip		Description	Note
	Material	Emitting Color		
PDC302-CxPG05	InGaN	True Green	Common Cathode x=C / Common Anode x=A	Add "BFWS" to end of part number for Black Face, White Segment version
PDC302-CxPG17	AlInGaP	Yellow Green		
PDC302-CxPY04		Yellow		
PDC302-CxPA11		Amber		
PDC302-CxPR02		Orange-Red		
PDC302-CxPR11		Red		
PDC302-CxPR21		Deep Red		

**Absolute Maximum Ratings at Ta=25°C**

Parameter	Symbol	Rating		Unit
		G17/Y04/A11/R02/R11/R21	G05	
Power Dissipation per Dice	P <sub>AD</sub>	70	114	mW
Derating Liner from 25°C per Dice	--	0.33	0.4	mA/°C
Continuous Forward Current Per Dice	I <sub>AF</sub>	25	30	mA
Peak Current Per Dice (duty cycle 1/10, 1KHz)	I <sub>PF</sub>	90	100	mA
Reverse Voltage Per Dice	VR	5	5	V
Electrostatic Discharge (HBM)	ESD	/	1000	V
Operating Temperature	Topr	-35~+85#		°C
Storage Temperature	Tstg	-35~+85#		°C

Solder Conditions: 1/16 inch below seating plane for 3 -5 seconds at 260°C.

**Electrical and Optical Characteristics at Ta=25°C**

Parameter	Symbol	Chip	Min.	Typ.	Max.	Unit	Condition
Forward Voltage Per Segment	VF	G05	--	3.2	3.8	V	IF=20mA
		G17/Y04/A11/R02/R11/R21	--	2	2.8		
Luminous Intensity Per Segment	Iv	G05	--	120	--	mcd	IF=10mA
		G17	--	6	--		
		Y04	--	30	--		
		A11	--	45	--		
		R02	--	20	--		
		R11	--	12	--		
		R21	--	10	--		
Peak Emission Wavelength / Dominant Wavelength	$\lambda P/\lambda d$	G05	--	*/525	--	nm	IF=20mA
		G17	--	572/570	--		
		Y04	--	592/590	--		
		A11	--	612/605	--		
		R02	--	632/625	--		
		R11	--	644/630	--		
		R21	--	660/645	--		
Reverse Current	IR		--	--	100	$\mu$ A	VR=5V
Luminous Intensity Matching Ratio	Iv-m		--	--	2:1	--	IF=10mA

### Typical Electrical/Optical Characteristic Curves

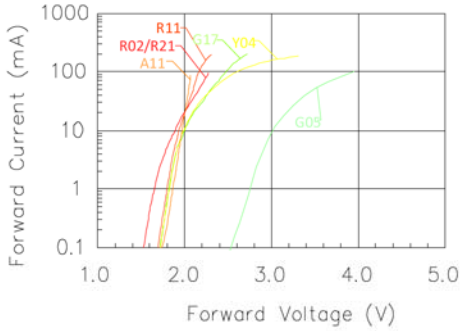


Fig 1. Forward Current vs. Forward Voltage

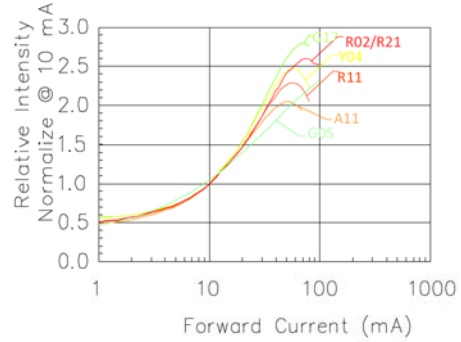


Fig 2. Relative Intensity vs. Forward Current

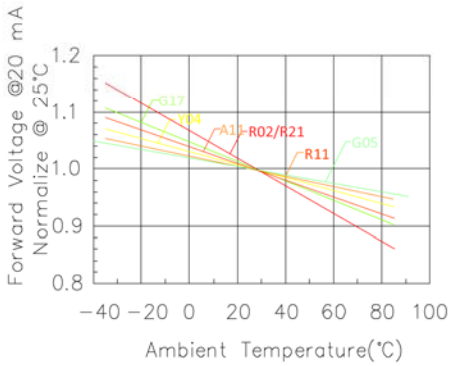


Fig 3. Forward Voltage vs. Temperature

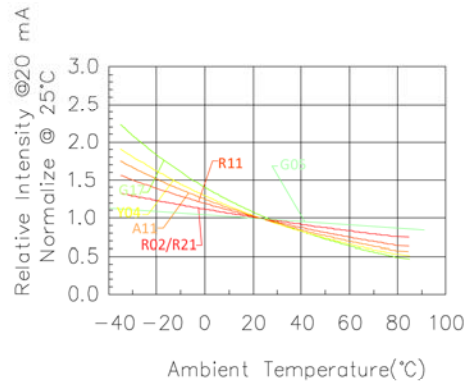


Fig 4. Relative Intensity vs. Temperature

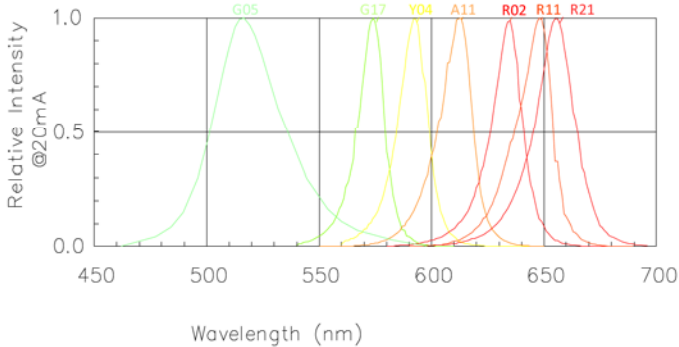


Fig 5. Relative Intensity vs. Wavelength

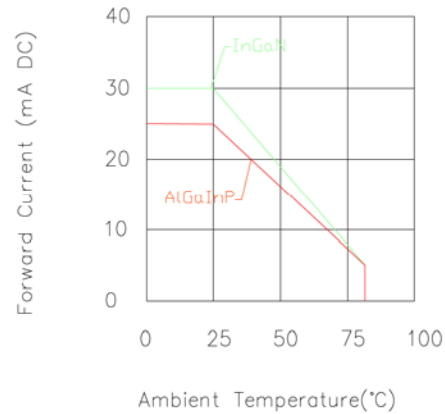


Fig 3. Forward Current vs. Ambient Temperature



**Luminous General lv Bin Grade (IF = 10mA)**

**Color Rank Limits (IF=20mA)**

Remark: Unit=mcd

\*Tolerance: ±20%

Remark: Unit=nm

\*Tolerance: ±1

● Pure Green(G05)

P	Q	R
70.555	112.889	180.623
112.888	180.622	288.996

1	2	3	4	5
515.0	517.0	519.0	521.0	523.0
517.0	519.0	521.0	523.0	525.0

● Yellow Green(G17)

G	H	J
2.627	4.204	6.727
4.203	6.726	10.763

0	1	2	3	4
567.5	569.5	570.5	571.5	573.0
569.4	570.4	571.4	572.9	575.0

● Yellow (Y04)

L	M	N
17.224	27.559	44.096
27.558	44.095	70.554

1	2	3	4	5
583.0	585.0	587.0	589.0	591.0
585.0	587.0	589.0	591.0	593.0

● Amber (A11)

L	M	N
17.224	27.559	44.096
27.558	44.095	70.554

● Orange (R02)

K	L	M
10.764	17.224	27.559
17.223	27.558	44.095

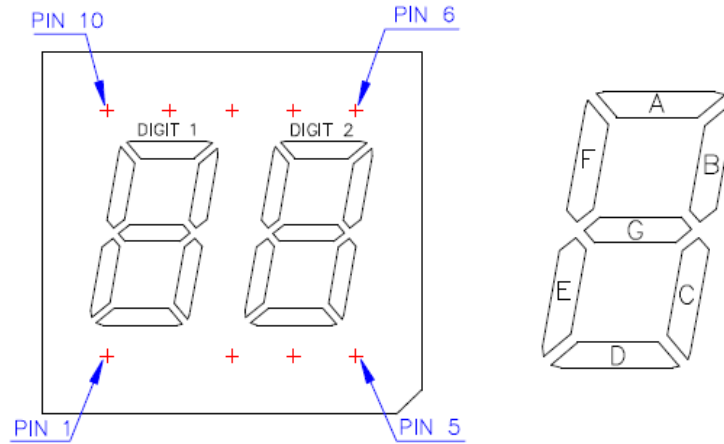
● Red (R11)

J	K	L
6.727	10.764	17.224
10.763	17.223	27.558

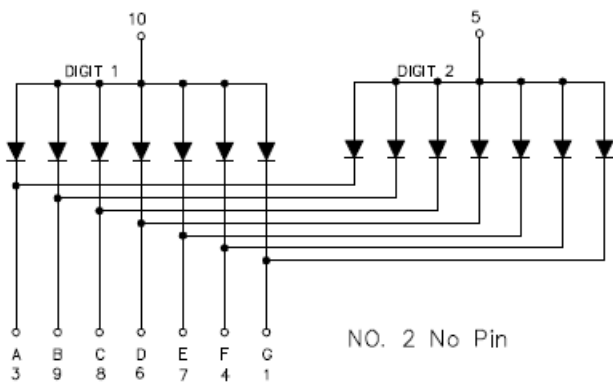
● Deep Red(R21)

H	J	K
4.204	6.727	10.764
6.726	10.763	17.223

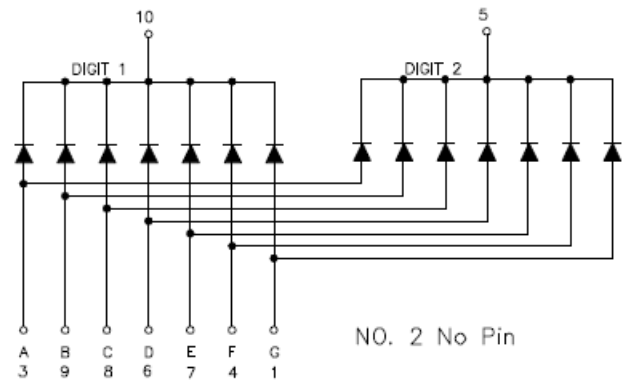
**All Light-On Segments Feature & Pad Position**



**Internal Circuit Diagram**



**Common Anode**



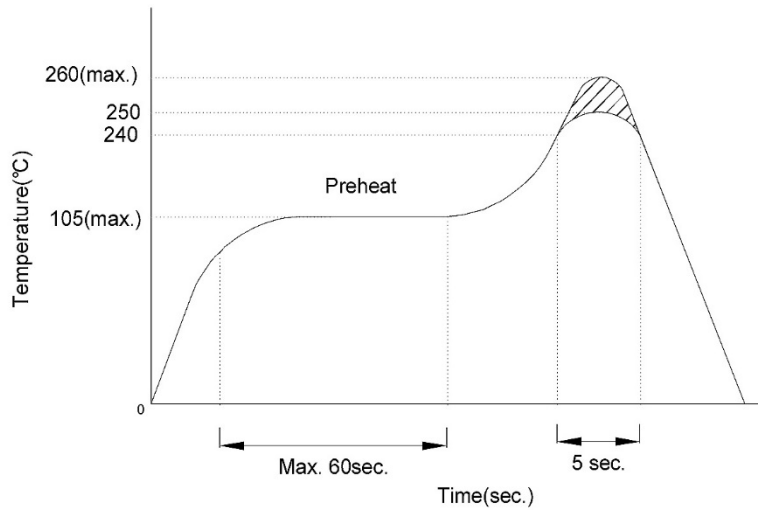
**Common Cathode**

### *Precautions for Use*

#### 1. Recommended soldering conditions

##### 1.1. Wave soldering

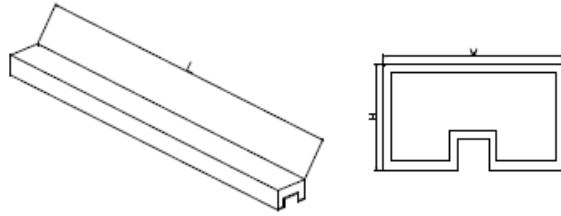
Basic SPEC is  $\leq 5$ sec. When  $260^{\circ}\text{C}$ . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1$ sec.).



##### 1.2. Soldering Iron:

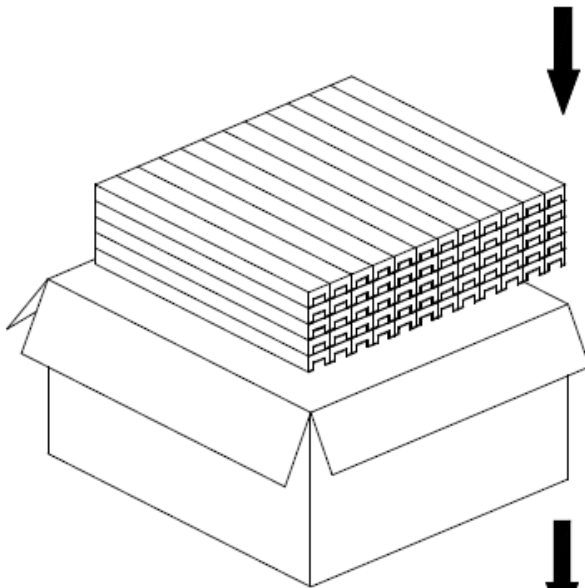
Power dissipation of iron should be smaller than 15W and temp should be controllable. Soldering temperature should be under  $260^{\circ}\text{C}$ , time  $\leq 3$ sec.

### *Packing Dimensions*



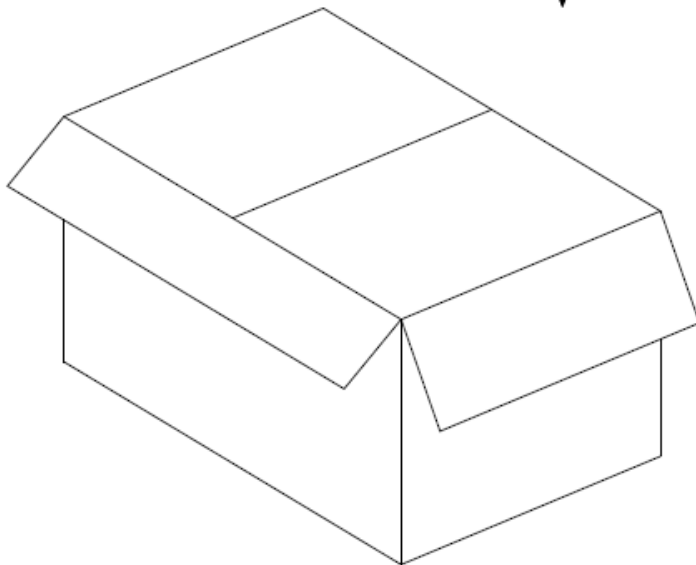
1 Tube From Box = 32PCS

Tube SIZE:  
L520XW15XH15.5mm



112 Tubes Per Inner Box  
Q'TY 3584 PCS

Box SIZE:  
L530 X W265 X H155mm



2 Boxes Per Carton  
TOTAL Q'TY 7168 PCS

Carton SIZE:  
L540 X W345 X H290mm

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